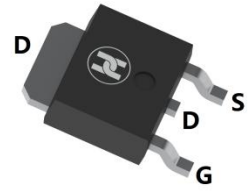
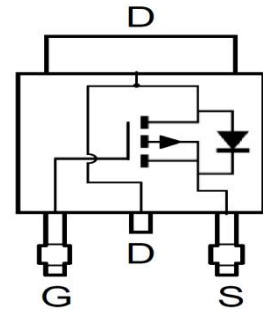


P-CHANNEL HIGH VOLTAGE MOSFET
FEATURES

- $V_{DS}=-100V, R_{DS(ON)}\leq 350m\Omega @ V_{GS}=-10V, I_D=-3.9A$
- Low Input Capacitance and Fast switching speed
- Low gate drive
- For Power Management Functions and DC-DC Converters Applications
- For Disconnect switches and Motor control Applications
- Surface Mount device


TO-252

MECHANICAL DATA

- Case: TO-252(DPAK)
- Case Material: Molded Plastic. UL flammability
- Classification Rating: 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.33 grams (approximate)

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	-100	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current, $V_{GS} = -10V$	I_D	$T_A = +25^\circ\text{C}(\text{Note}2)$	-3.9
		$T_A = +70^\circ\text{C}(\text{Note}2)$	-3.1
		$T_A = +25^\circ\text{C}(\text{Note}1)$	-2.4
Pulsed drain current $V_{GS} = -10V$	I_{DM}	-11.3	A
Maximum Body Diode Forward Current	I_S	-8.7	A
Pulsed source current (body diode)	I_{SM}	-11.3	A
Power dissipation	P_D	$T_A = +25^\circ\text{C}(\text{Note}1)$	4.0
		$T_A = +25^\circ\text{C}(\text{Note}2)$	10.2
		$T_A = +25^\circ\text{C}(\text{Note}5)$	2.0
Thermal resistance from Junction to ambient	$R_{\theta JA}$	(Note1)	31
		(Note2)	12.3
		(Note5)	62
Thermal Resistance, Junction to Case (Note4)	$R_{\theta JL}$	2.4	$^\circ\text{C}/\text{W}$
Operating and Storage temperature	T_J, T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

2. Same as note (1), except the device is measured at $t \leq 10$ sec.

3. Same as note (1), except the device is pulsed with $D = 0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.

4. Thermal resistance from junction to solder-point (at the end of the drain lead).

5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

P-CHANNEL HIGH VOLTAGE MOSFET
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
OFF characteristics						
Drain-Source breakdown voltage	V _{(BR)DSS}	-100			V	V _{GS} =0V, I _D =-250μA
Zero gate voltage drain current	I _{DSS}			-0.5	μA	V _{DS} =-100V, V _{GS} =0V
Gate-body leakage current	I _{GSS}			±100	nA	V _{DS} =0V, V _{GS} =±20V
ON characteristics						
Gate-threshold voltage	V _{GS(th)}	-2.0		-4.0	V	V _{DS} =V _{GS} , I _D =-250μA
Drain-source on-resistance (Note6)	R _{DS(on)}			350	mΩ	V _{GS} =-10V, I _D =-1.4A
				450	mΩ	V _{GS} =-6V, I _D =-1.2A
Forward trans-conductance(Note6&7)	g _{fs}		2.8		S	V _{DS} =-15V, I _D =-1.4A
Dynamic characteristics(Note7)						
Input capacitance	C _{iss}		424		pF	V _{DS} =-50V, V _{GS} =0V, f=1MHz
Output capacitance	C _{oss}		36.6		pF	
Reverse transfer capacitance)	C _{rss}		29.8		pF	
Switching characteristics (Note7&8)						
Turn-on delay time	t _{d(on)}		3.0		nS	V _{DD} =-50V, I _D =-1A, R _g =6.0Ω, V _{GS} =-10V
Turn-on rise time	t _r		3.5		nS	
Turn-off delay time	t _{d(off)}		13.4		nS	
Turn-off fall time	t _f		7.2		nS	
Total gate charge	Q _g		7.1		nC	V _{DS} =-50V, V _{GS} =-6V, I _D =-1.4A
Total gate charge	Q _g		10.7		nC	V _{DS} =-50V, V _{GS} =-10V, I _D =-1.4A
Gate-source charge	Q _{gs}		1.7		nC	
Gate-drain charge	Q _{gd}		3.8		nC	
Source-drain diode characteristics						
Diode forward voltage (Note6)	V _{SD}		-0.85	-0.95	V	I _S =-1.7A, V _{GS} =0V
Body Diode Reverse Recovery Time(Note7)	t _{rr}		33		nS	I _S =-1.5A, dI/dt= 100A/μs
Body Diode Reverse Recovery Charge(Note7)	Q _{rr}		48		nC	

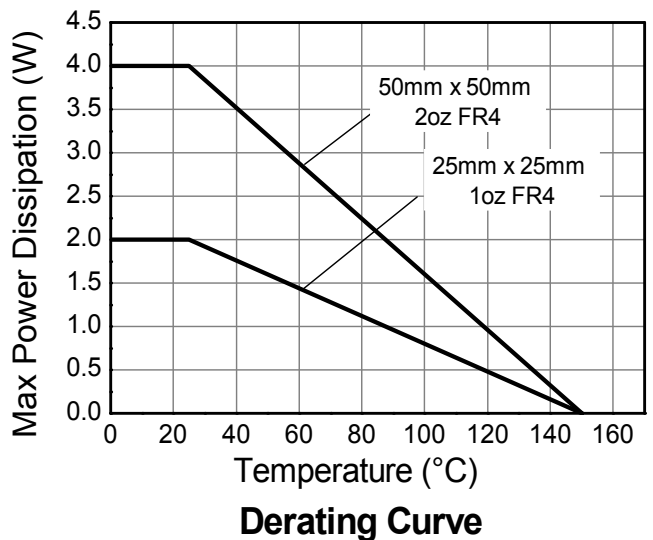
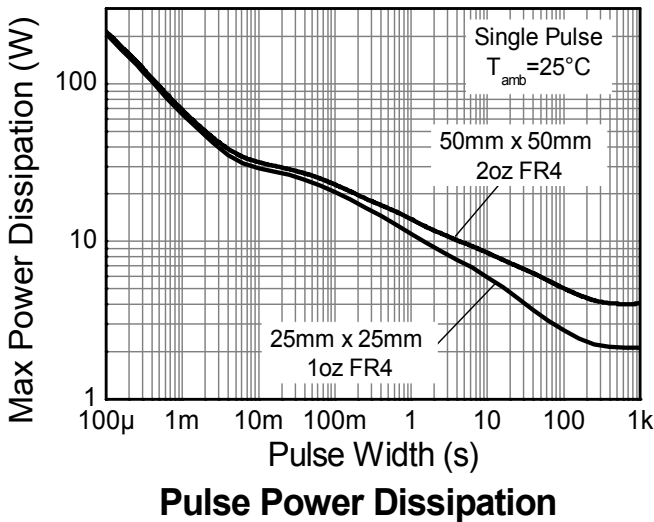
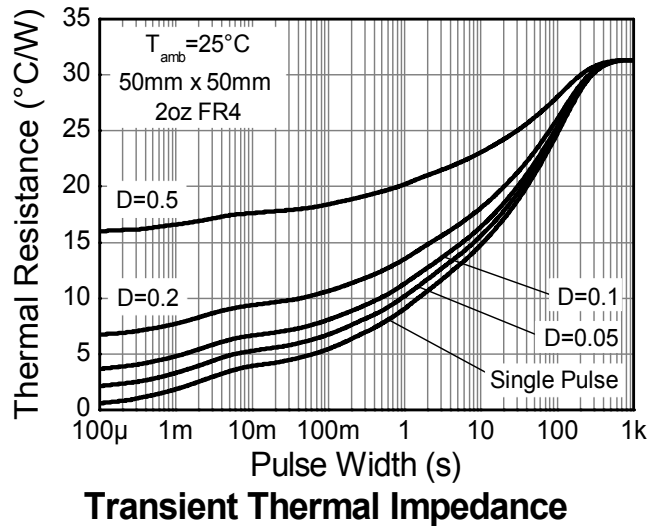
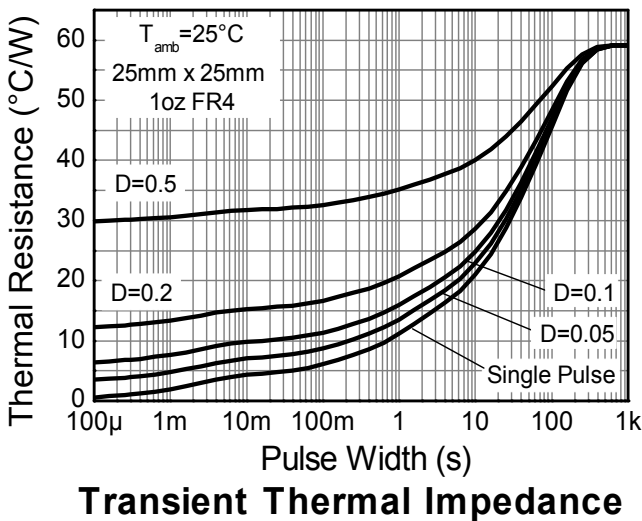
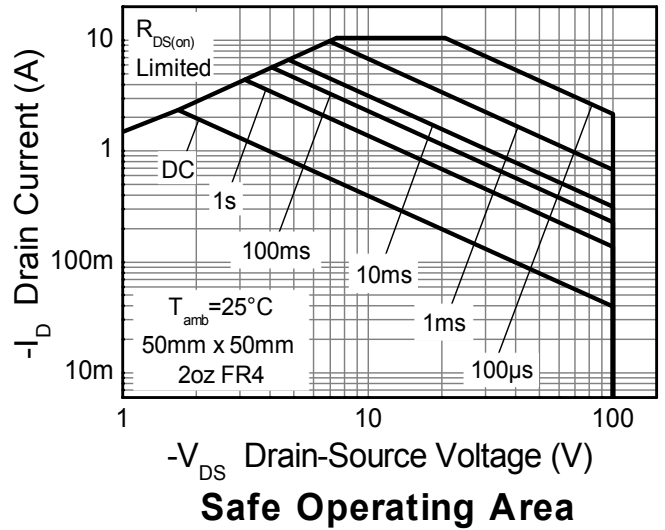
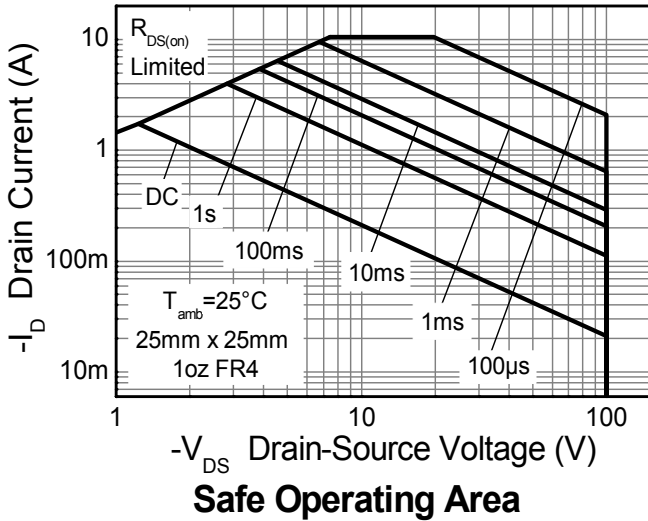
Notes: 6. Measured under pulsed conditions. Pulse width≤300μs; duty cycle≤2%.

7. For design aid only, not subject to production testing.

8. Switching characteristics are independent of operating junction temperature.

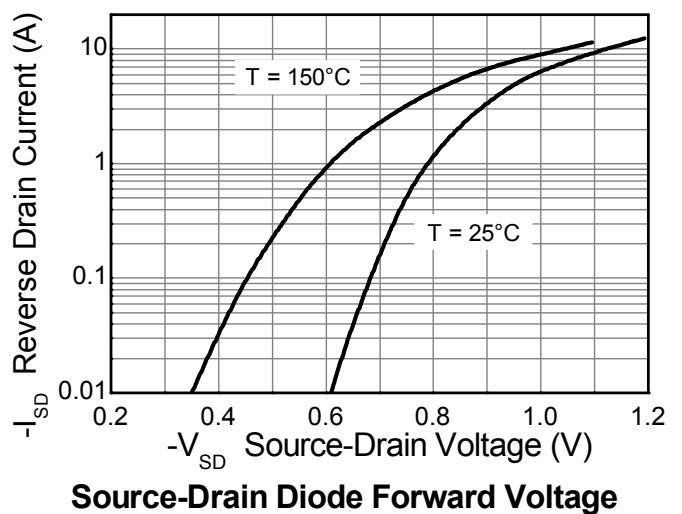
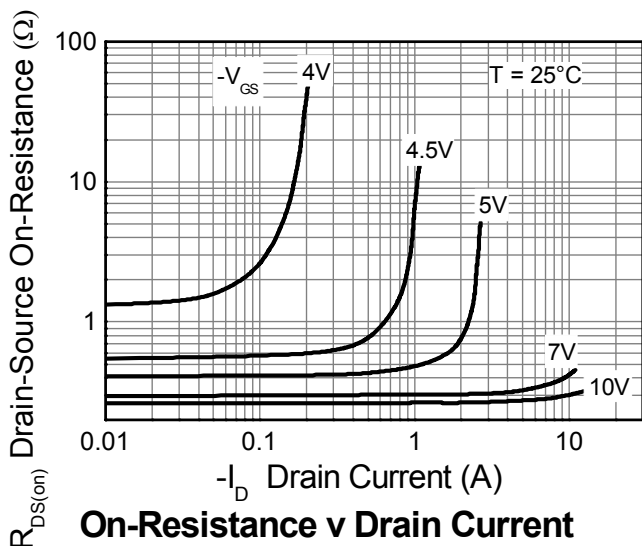
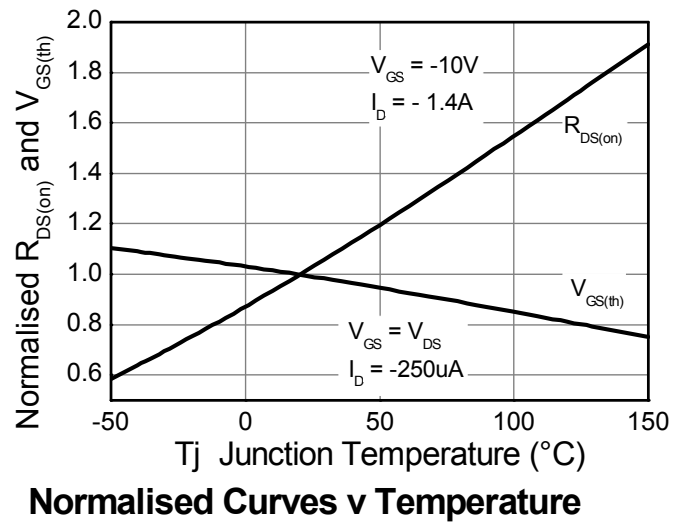
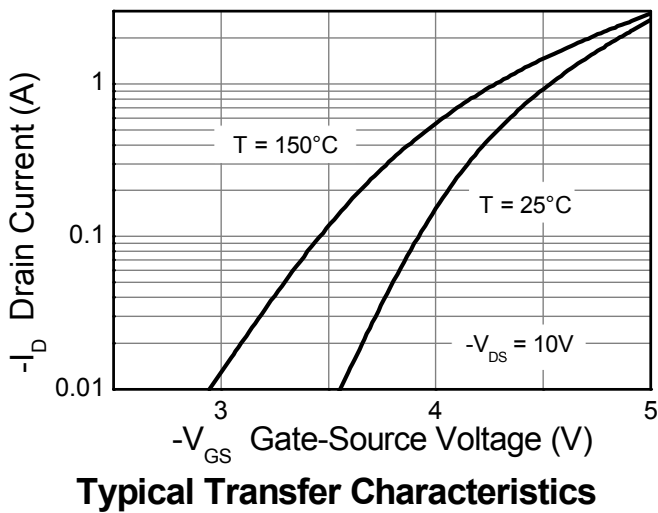
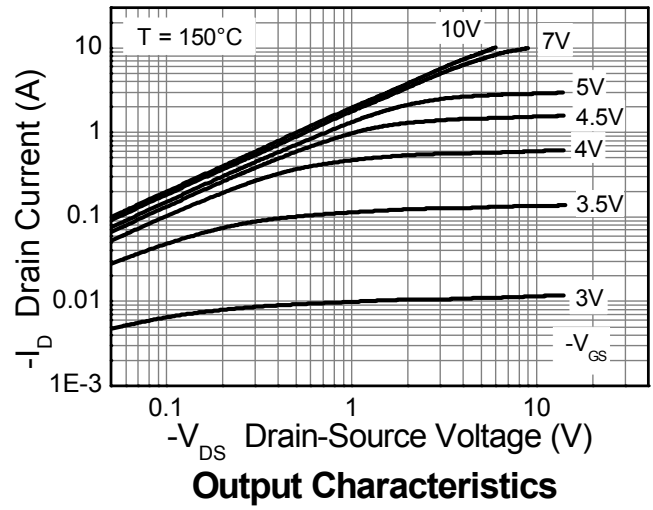
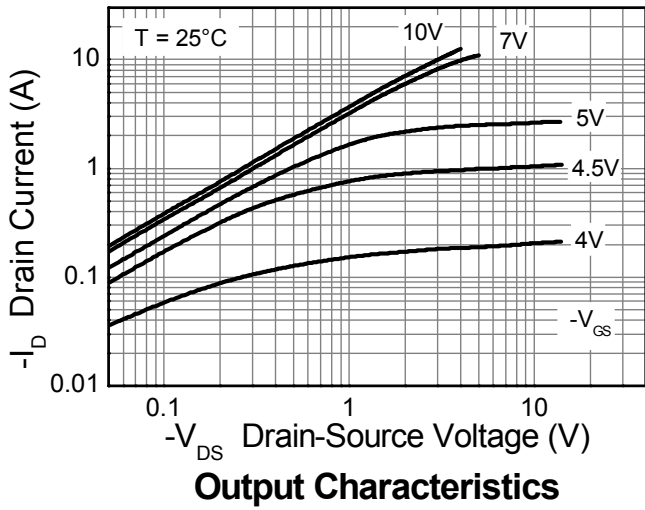
P-CHANNEL HIGH VOLTAGE MOSFET

Thermal Characteristics



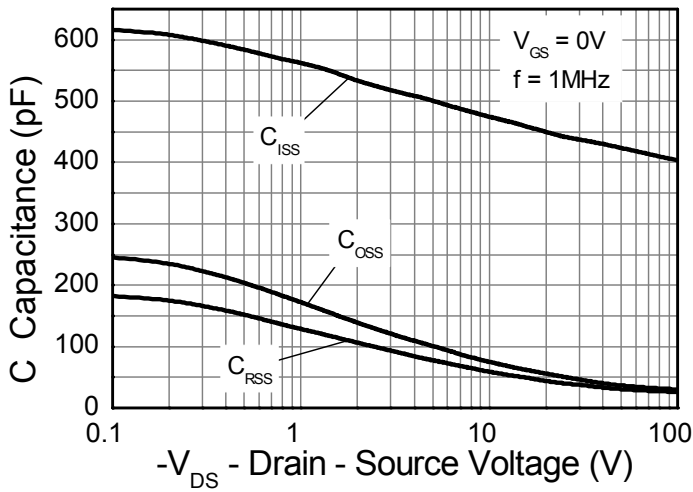
P-CHANNEL HIGH VOLTAGE MOSFET

Typical Characteristics

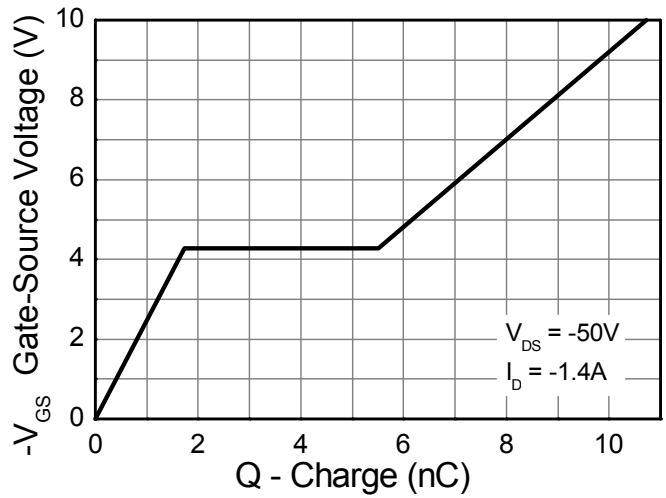


P-CHANNEL HIGH VOLTAGE MOSFET

Typical Characteristics

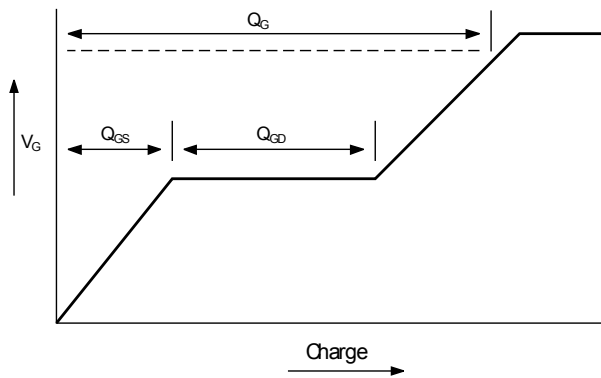


Capacitance v Drain-Source Voltage

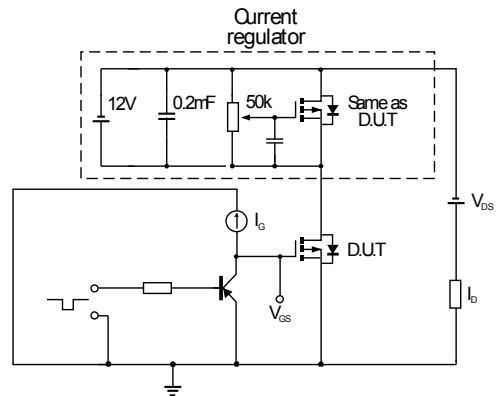


Gate-Source Voltage v Gate Charge

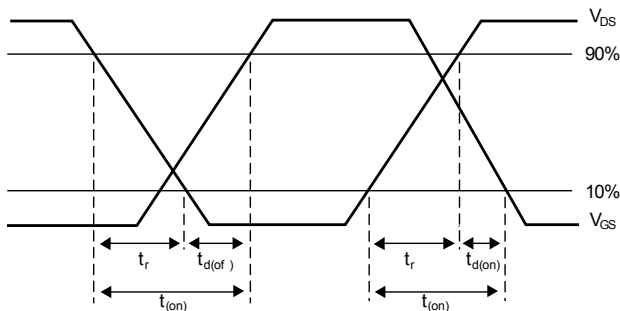
Test Circuits



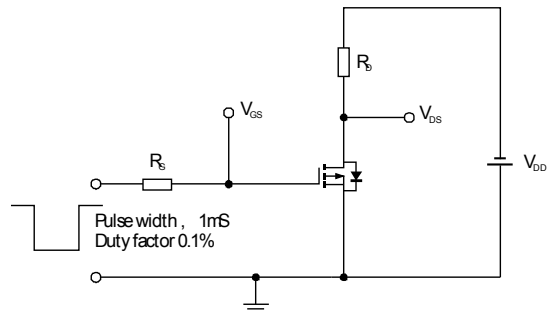
Basic gate charge waveform



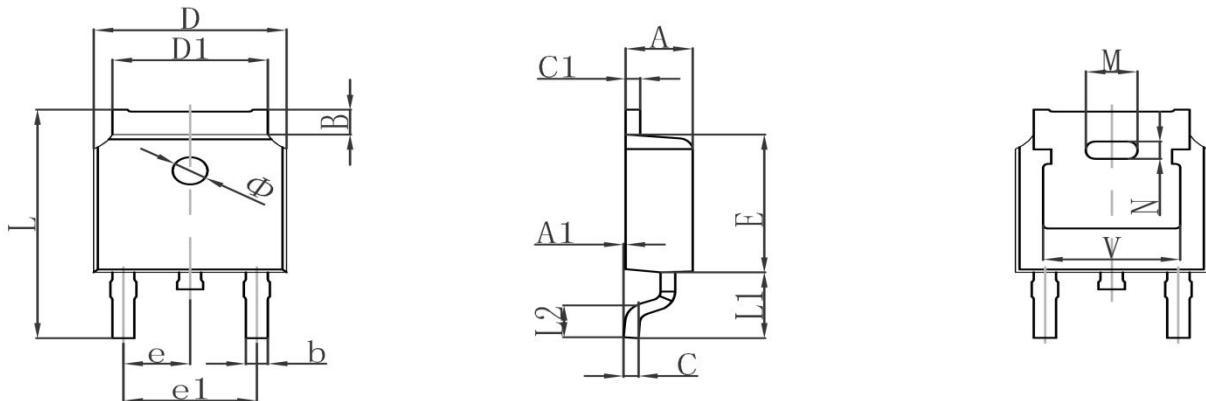
Gate charge test circuit



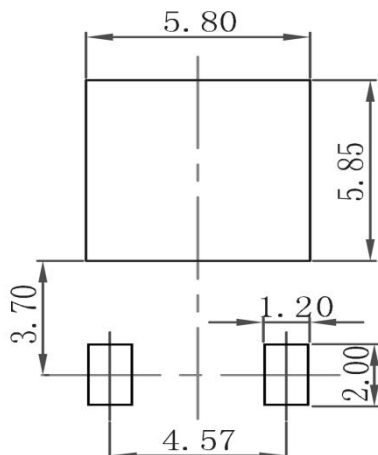
Switching time waveforms



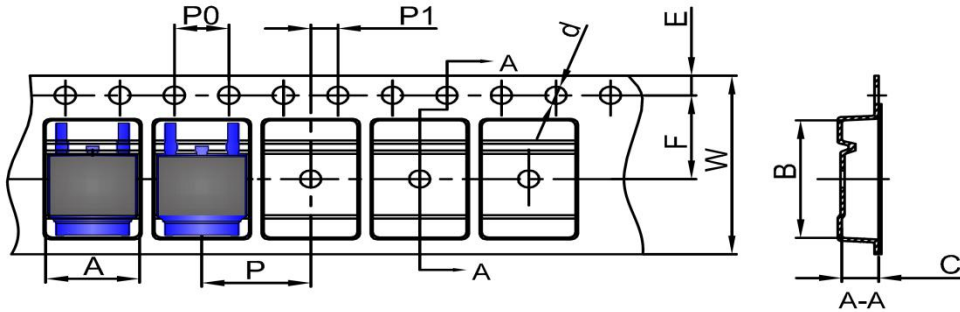
Switching time test circuit

P-CHANNEL HIGH VOLTAGE MOSFET
TO-252 Package Outline Dimensions


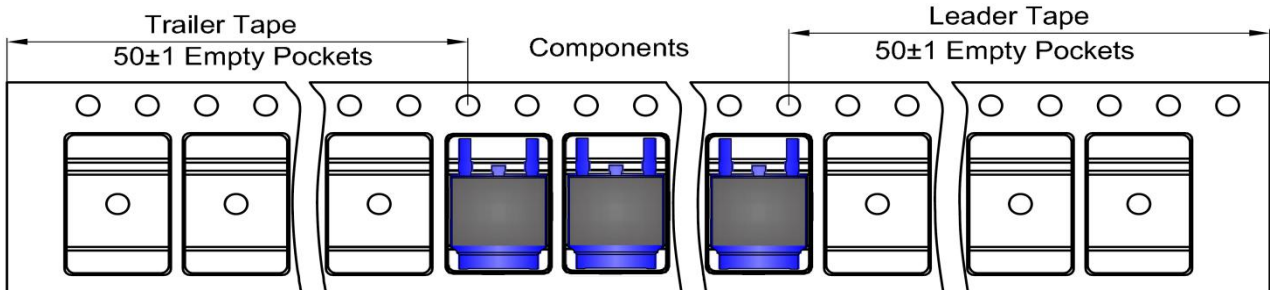
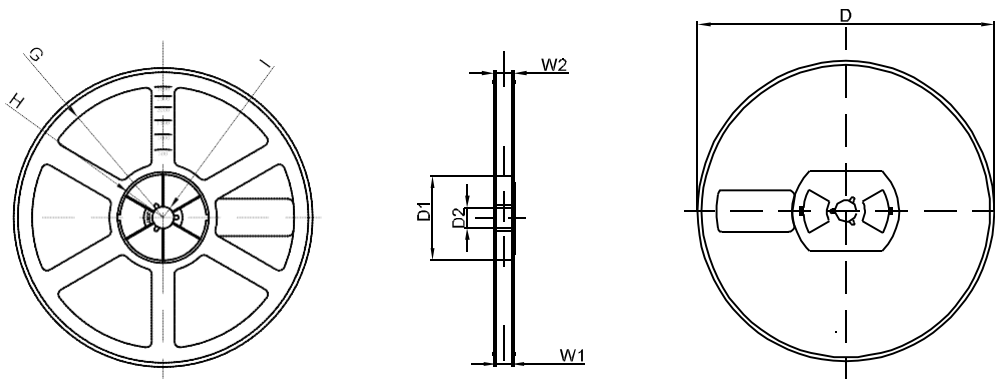
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.380	0.087	0.094
A1	0.000	0.100	0.000	0.004
B	0.800	1.400	0.031	0.055
b	0.710	0.810	0.028	0.032
c	0.460	0.560	0.018	0.022
c1	0.460	0.560	0.018	0.022
D	6.500	6.700	0.256	0.264
D1	5.130	5.460	0.202	0.215
E	6.000	6.200	0.236	0.244
e	2.286TYP		0.090TYP	
e1	4.327	4.727	0.170	0.186
M	1.778REF		0.070REF	
N	0.762REF		0.018REF	
L	9.800	10.400	0.386	0.409
L1	2.9REF		0.114REF	
L2	1.400	1.700	0.055	0.067
V	4.830REF		0.190REF	
Φ	1.100	1.300	0.043	0.051

TO-252 Suggested Pad Layout

Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

P-CHANNEL HIGH VOLTAGE MOSFET
TO-252 Tape and Reel
TO-252 Embossed Carrier Tape


DIMENSIONS ARE IN MILLIMETER										
TYPE	A	B	C	d	E	F	P0	P	P1	W
TO-252	6.90	10.50	2.70	Ø1.55	1.75	7.50	4.00	8.00	2.00	16.00
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

TO-252 Tape Leader and Trailer

TO-252 Reel


DIMENSIONS ARE IN MILLIMETER								
REEL OPTION	D	D1	D2	G	H	I	W1	W2
13" DIA	Ø330.00	100.00	Φ21.00	R151.00	R56.00	R6.50	16.40	21.00
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1